Singapore Asahi Chemical & Solder Industries Pte Ltd

Asahi Products-Liquid Flux

		Dipping	No-Clean						Water Soluble			VOC Free
	Formula	**FL6000**	**QF2018M**	**QF2036**	**FL2002T**	**QF2055**	**FL2012M2**	**QF3115A**	**T5A**	**T3018**	**WF6033**	**WBF4008**
Product Features		Incorporated with organic activators for improved solderability by reducing the surface tension of the solder during the tinning process.	Specially designed to give a clear residue with superior wetting on difficult to solder substrates.	Flux residue is clear and non sticky. Minimizes micro-solderballs during conventional and lead free PCB assemblies.	Formulated for both leaded and lead free application. It reduces solder bridging problems with no solder balls formed.	Halogen free flux which minimizes micro-solderballs during conventional and lead free PCB assemblies.	Excellent solderability with a Matte finish. Reduces bridging in connectors and QFPs.	One of our first generation flux for both Conventional and lead free soldering. No solder ball formation and minimum bridging issues.	A fumeless and non-flamable aqueous solution to restore the solderability of tarnished copper surface for hot solder dipping process.	A halide free, alcohol based flux for dipping applications on component leads made of Nickel-Iron (Alloy 42), Nickel and Copper.	Highly active flux designed for wave soldering operations. Excellent capillary effect on plated-through-hole PCBs.	A VOC free / water-based, no-clean flux designed for mass production in leaded and lead-free application.
	Flux Type	Low-Solid, No-Clean	Low Solid, Halie-Free, No-Clean	Low Solid, Halie-Free, No-Clean	No-Clean	Halogen-Free, No-Clean	No-Clean	No-Clean	Water Soluble	Water Soluble	Water Soluble	VOC Free / Water-Based
Properties	**Solid Content (%)** JIS Z 3197 8.1.3	2.0 ± 0.5	2.2 ± 0.2	3.6 ± 0.2	7.0 ± 0.5	5.3 ± 0.5	10.0 ± 0.5	15.0 ± 0.5	2.1 ± 0.3	10.6 ± 0.5	20.5 ± 1.0	3.0 ± 0.5
	Specific Gravity JIS Z 3197 8.2.2	0.823 ± 0.005	0.788 ± 0.005	0.792 ± 0.005	0.811 ± 0.005	0.797 ± 0.005	0.813 ± 0.005	0.823 ± 0.005	1.02 ± 0.005	0.879 ± 0.005	0.86 ± 0.005	1.008 ± 0.005
	Halide Content (wt%) JIS Z 3197 8.1.4.2.1	0.08 ± 0.01	Not Added	< 0.01	0.09 ± 0.01	Not Added	0.08 ± 0.01	0.08 ± 0.01	1.90 ± 0.1	Not Added	2.0 ± 0.03	Not Added
	SIR (85°C, 85%RH,168hrs) IPC-TM-650 2.6.3.3	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω
	ECM (85°C, 88.5%RH, 596hrs) IPC-TM-650 2.6.14.1	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth
	Flux Activity Classification IPC J-STD-004	ROM1	ROM0	ROM0	ROM1	REL0	ROM1	ROM1	INH1	ORH0	ORH1	ORM0
	Spread Factor JIS Z 3197 8.3.1.1	>85% (SnPb)	>70%	>75%	>85% (SnPb)	>70%	>75%	>80%	>85% (SnPb)	>80% (SnPb)	>80% (SnPb)	>70%
Applications & Appearance	**Surface Finish**	Shiny	Shiny	Shiny	Shiny	Shiny	Matte	Matte	Matte	Slightly Matte	Shiny	Shiny
	Residue Removal	Not Required	Not Required	Not Required	Not Required	Not Required	Not Required	Not Required	Removal with plain water at 60°C +/- 5°C	Removal with plain water at 60°C +/- 5°C	Removal with plain water at 60°C +/- 5°C	Not Required
	Application	Component Lead Tinning	Spraying, Dipping	Spraying, Foaming, Dipping, Component Lead Tinning	Spraying, Dipping	Spraying, Foaming, Dipping	Spraying, Foaming, Dipping	Spraying, Foaming, Dipping	Wire and Component Lead Tinning	Wire and Component Lead Tinning	Spraying, Foaming, Dipping	Spraying, Dipping
	Solvent	#6000	#2000	#2000	#2002	#2000	#2000	#2000	-	-	#3000	-